

Electronic Patent Application Fee Transmittal

Application Number:	10598717			
Filing Date:	08-Sep-2006			
Title of Invention:	POLISHING PAD AND SEMICONDUCTOR DEVICE MANUFACTURING METHOD			
First Named Inventor/Applicant Name:	Tetsuo Shimomura			
Filer:	Daniel E. Altman/Hiroko Isetani			
Attorney Docket Number:	UNIU40.017APC			
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
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Claims:				
Miscellaneous-Filing:				
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Patent-Appeals-and-Interference:				
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Utility Appl issue fee	1501	1	1510	1510
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Total in USD (\$)				1810